

**Integrated chip package structure using silicon substrate and method of
manufacturing the same**

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|--------------|---|-----------------------|------------------|------|
| Appl. No. | : | 10/755,042 | Confirmation No. | 8665 |
| Applicant | : | Mou-Shiung Lin et al. | | |
| Filed | : | January 9, 2004 | | |
| TC/A.U. | : | 2815 | | |
| Examiner | : | Fenty, Jesse A | | |
| Docket No. | : | MEGP0004USA1 | | |
| Customer No. | : | 27765 | | |

Commissioner for Patents
P.O. Box 1450
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AMENDMENT

5 Sir:

In response to the Office action of June 22, 2006, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

10 **Remarks/Arguments** begin on page 9 of this paper.